

ABSTRACT

A semiconductor device comprises one or two semiconductor chips, each including an input circuit having
5 a wiring (3) for connecting an input pad (2) to an inner circuit, a first electrostatic protection element (1) electrically connected to the wiring, a second electrostatic protection element (1), and a fuse (4) provided between the wiring (3) and second electrostatic
10 protection element (1). When the semiconductor device has one semiconductor chip, the wiring (3) and second electrostatic protection element (1) are connected to each other through the fuse (4), and when the semiconductor device has said two semiconductor chips, the fuse (4) is
15 disconnected so that the second electrostatic protection element (1) is electrically disconnected from the wiring (3).